

# PATENT ABSTRACTS OF JAPAN

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## (54) SEMI-CONDUCTIVE RESIN MOLDED ARTICLE

### (57)Abstract:

**PROBLEM TO BE SOLVED:** To provide a semi-conductive resin molded article having a uniform resistance value in the semi-conductive region.

**SOLUTION:** The semi-conductive molded article is comprised by molding a conductive thermal plastic resin composition composed by mixing (C) the thermal plastic resin and/or a thermal plastic elastomer of 0.1–80 pts.wt. except the component (C) to a conductive resin component comprising (A) a matrix thermal plastic resin and (B) a fine carbon fiber having an average fiber diameter of 200 nm or less of 0.1–20 wt.%. The component 3 (C) is not completely dissolved with the component 1 (A) and is dispersed in a sea-island form, the component 3 (C) forms a dispersion phase in an island form and an average value of the short diameter Rmin of the dispersion phase of the component 3 (C) is 10  $\mu\text{m}$  or less.

